

SEMICONDUCTOR PACKAGE WITH EXPOSED DIE PAD AND BODY-LOCKING LEADFRAME

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ABSTRACT OF THE DISCLOSURE

A very thin, small outline, thermally enhanced semiconductor package includes a leadframe that is coined to form locking features on an exposed die pad and on a plurality of extremely narrow, closely spaced leads. The coined features improve the mechanical locking between the leadframe and the plastic body of the package to increase their resistance to delamination and subsequent penetration by moisture, and enable reliable wire bonds to be made to the otherwise extremely narrow leads.

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